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PATENT

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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application: Takahiro IJIMA et al.

Serial No.: 09/736,864

Filed: December 14, 2000

For: INTERCONNECTION SUBSTRATE  
HAVING METAL COLUMNS COVERED BY A  
RESIN FILM AND MANUFACTURING  
METHOD THEREOF

GRP ART UNIT : 281

Ex.: CHU, C.

**AFTER FINAL  
AMENDMENT**

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**Certification under 37 C.F.R. §1.8(a)**

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with The United States Postal Service with sufficient postage as first class mail in an envelope addressed to The Commissioner for Patents, Washington, D.C. 20231 on January 30, 2003.

*Vangelis Economou*  
Vangelis Economou, Reg. No. 32,341

Commissioner for Patents  
Washington, D.C. 20231

**AMENDMENT UNDER 37 C.F.R. §1.116**

Sir:

In response to the Office Action dated November 26, 2002, please amend the above-captioned application as follows:

**IN THE CLAIMS:**

Please substitute the following claims 1, 11 and 13 in clean copy format for the pending claims 1, 11 and 13. A marked up copy of the claims is attached to indicate the amendments.